FILE OROLIA ART_CARD

Réf PCB:	ART	CARD	Rev 5
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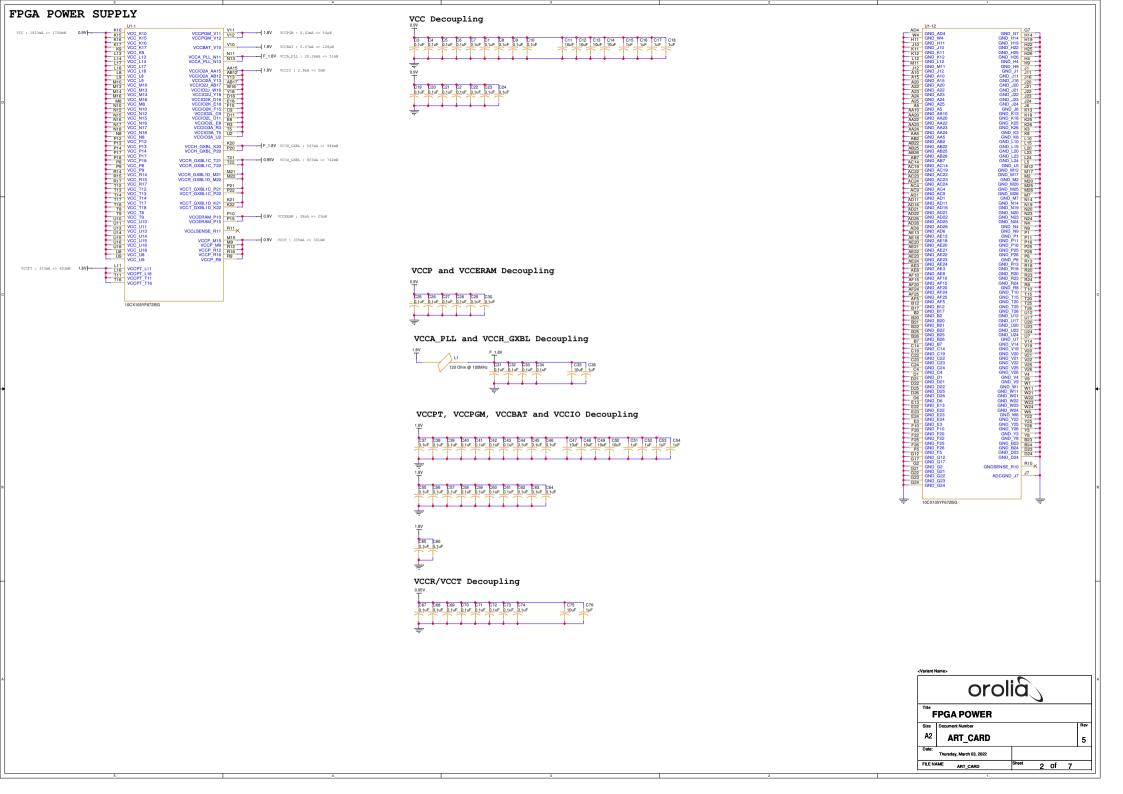
_	7	CLIEFTO OF ELECTRICAL	COLIENANTICO
<u> </u>	/	SHEETS OF ELECTRICAL	SCHEIMATICS

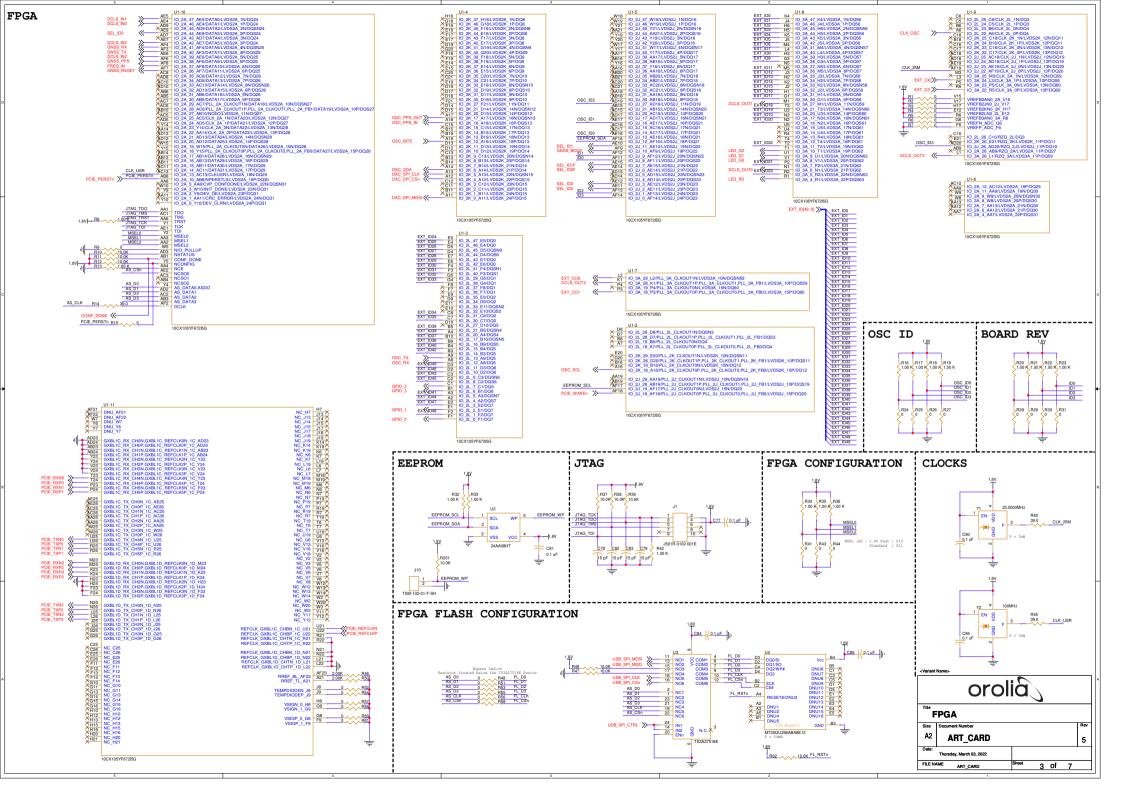
- □ ASSEMBLY DRAWING TOP
- □ ASSEMBLY DRAWING BOTTOM
- ⇒ 1 SILKSCREEN TOP
- ⇒ 1 SOLDER MASK TOP
- □ COPPER LAYER TOP
- □ COPPER LAYER INNER 1
- □ COPPER LAYER INNER 2
- ⇒ 1 COPPER LAYER INNER 3
- ⇒ 1 COPPER LAYER INNER 4
- ⇒ 1 COPPER LAYER INNER 5
- ⇒ 1 COPPER LAYER INNER 6
- □ COPPER LAYER BOTTOM
- ⇒ 1 SOLDER MASK BOTOM
- ⇒ 1 SILKSCREEN BOTTOM
- ⇒ 1 DRILL DRAWING

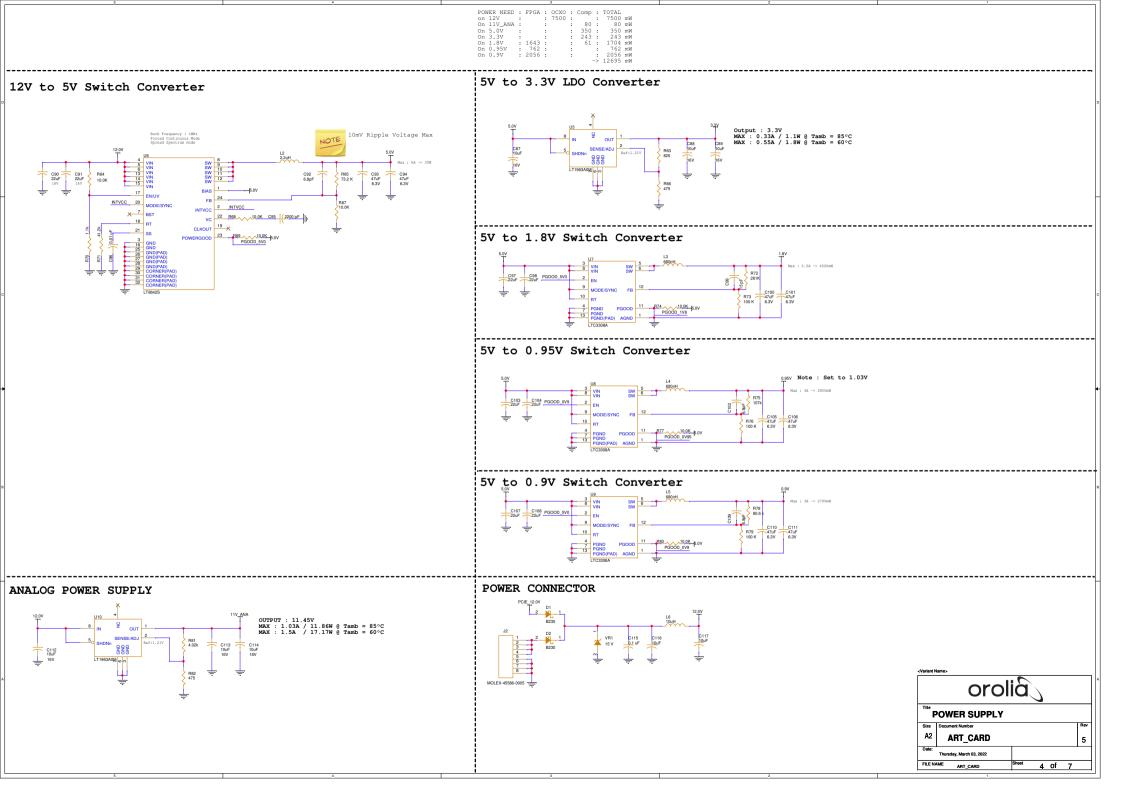


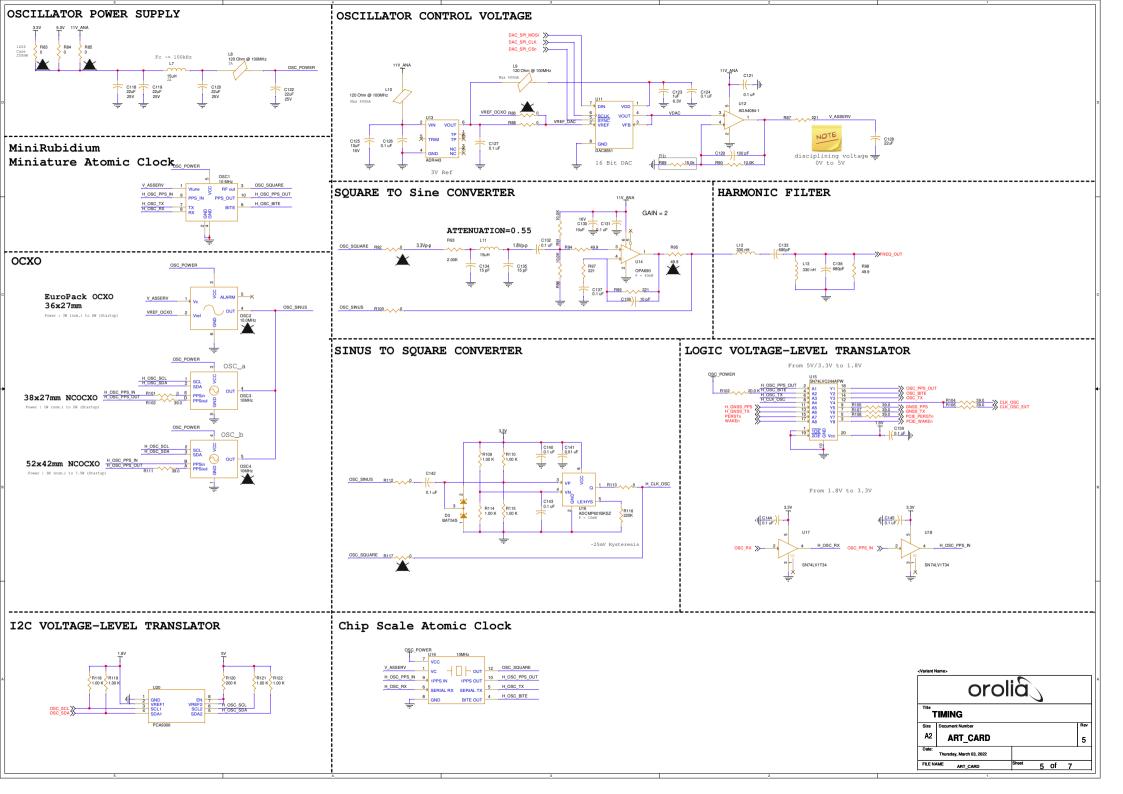
1 bis Avenue du Bois l'Abbé

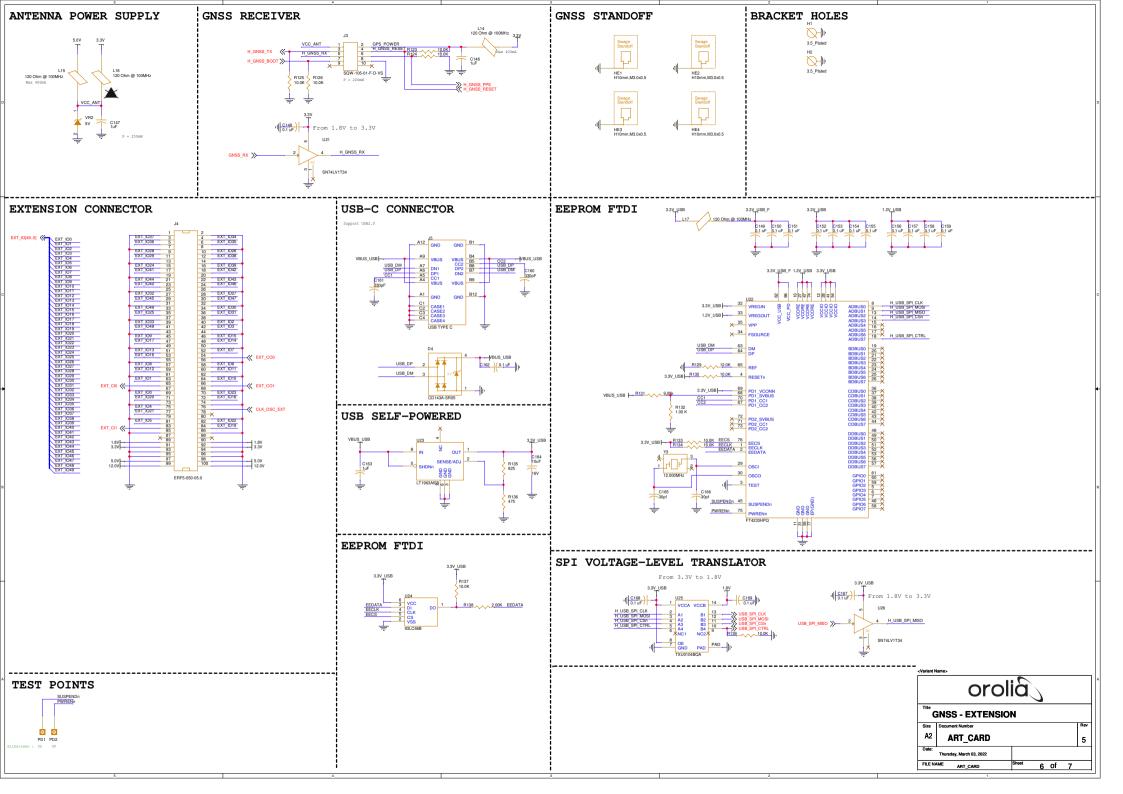


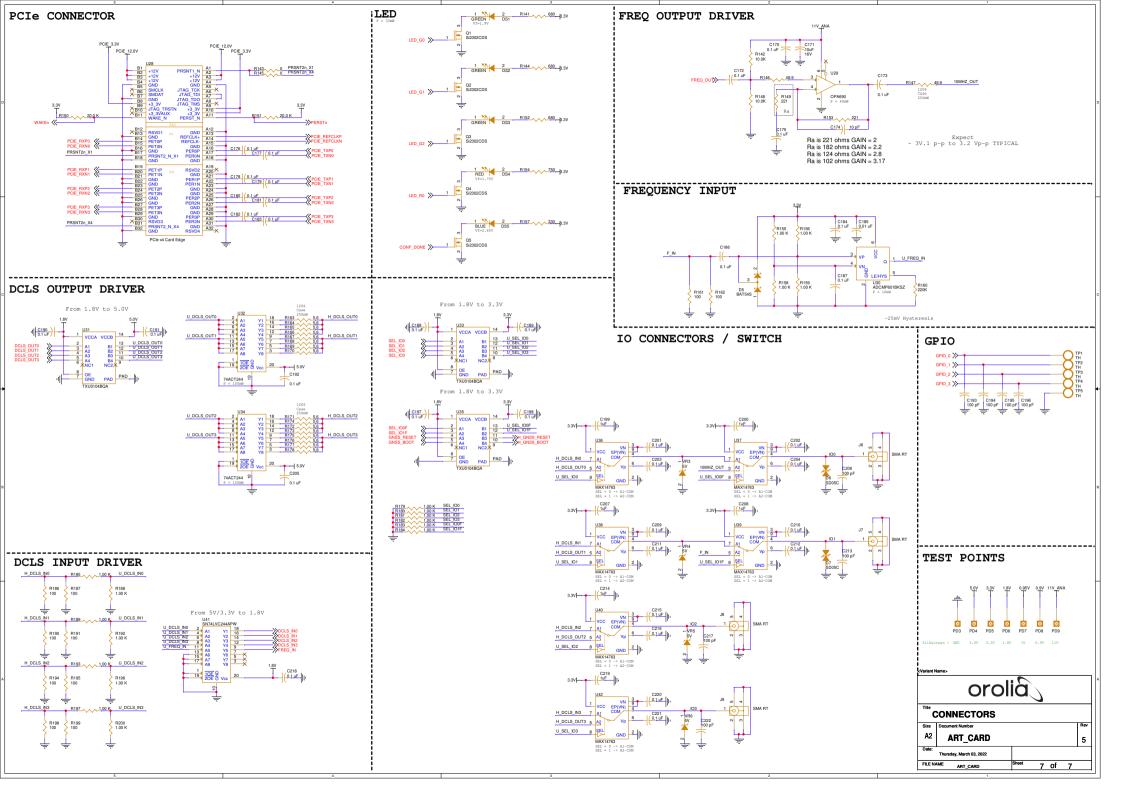


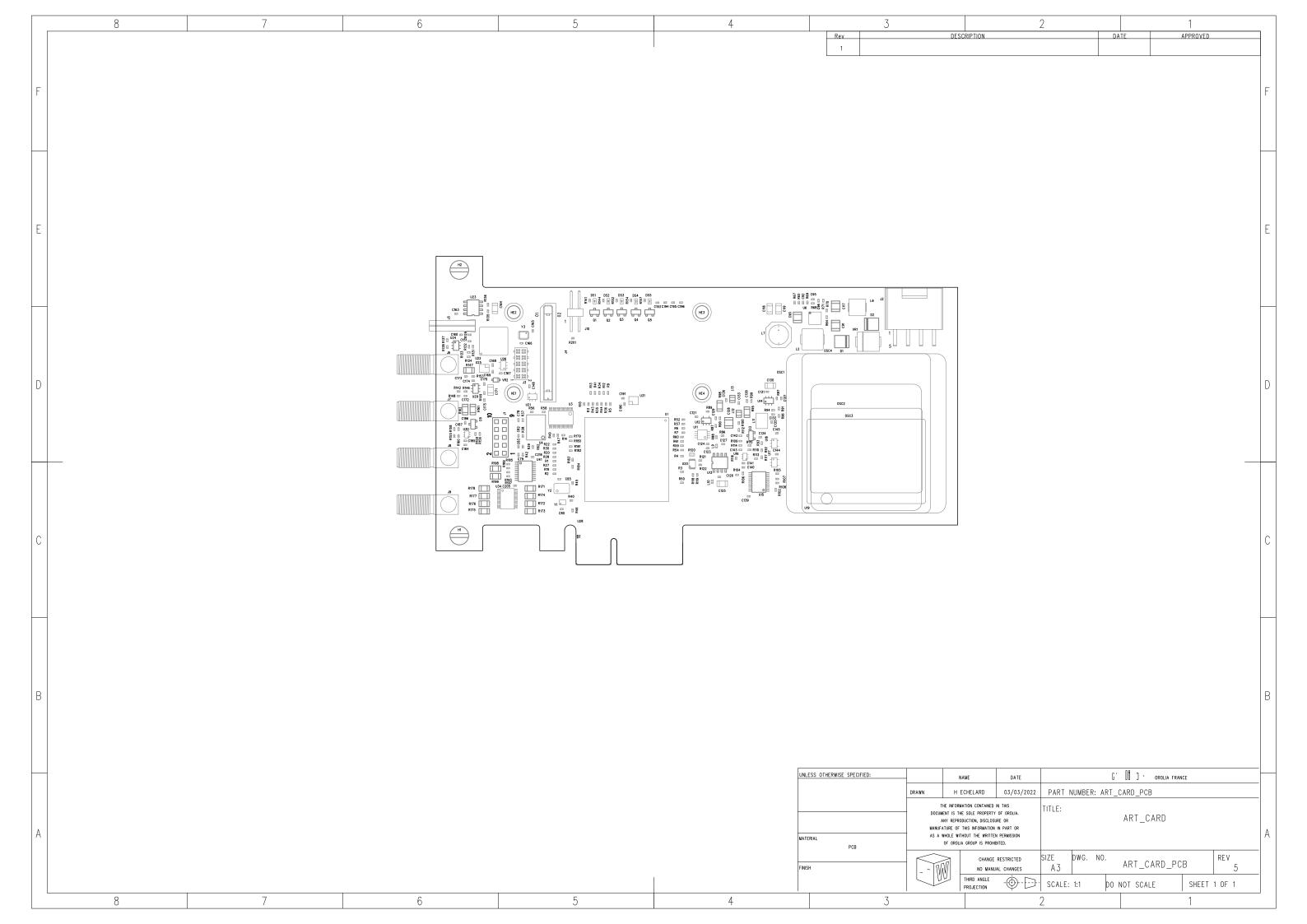


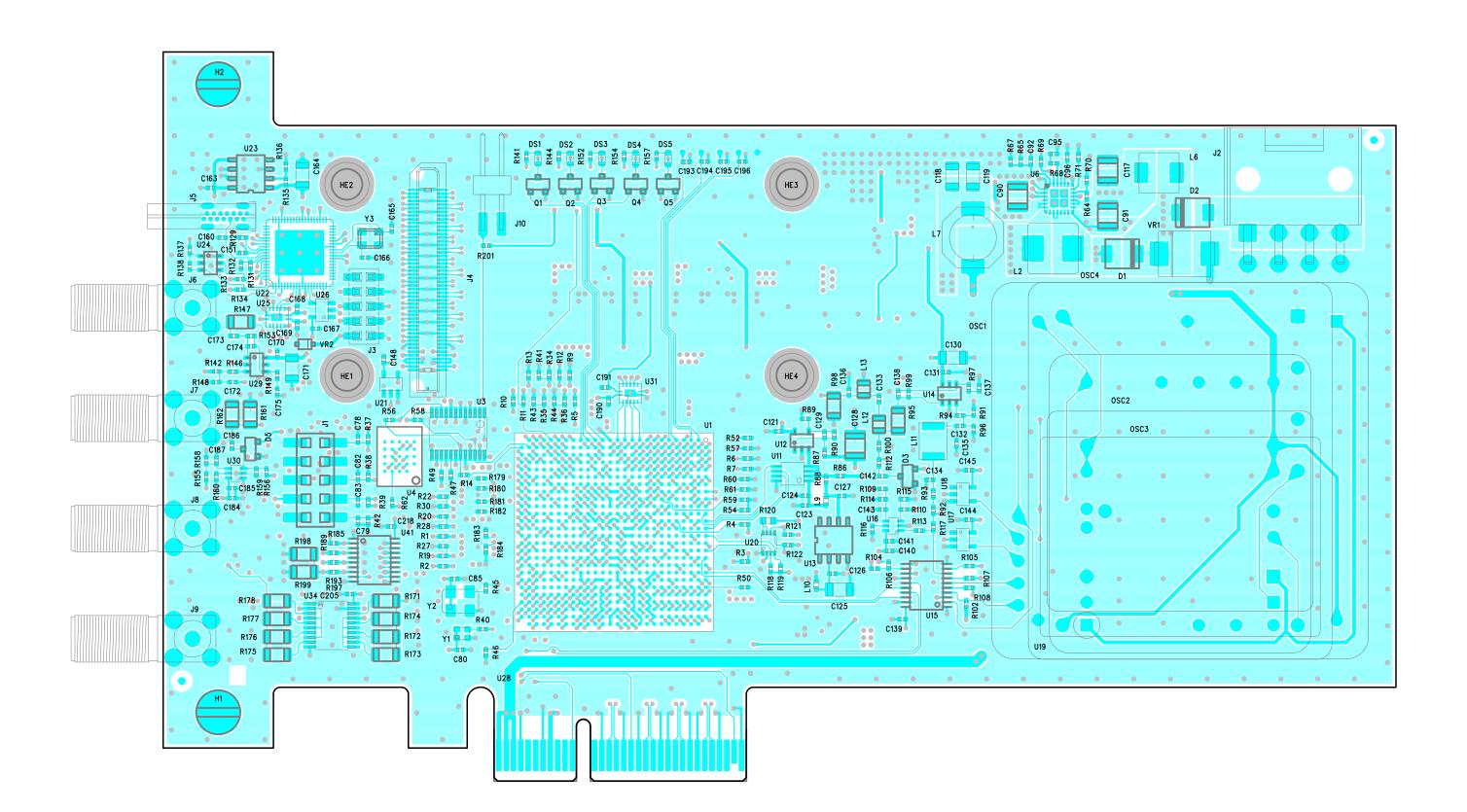


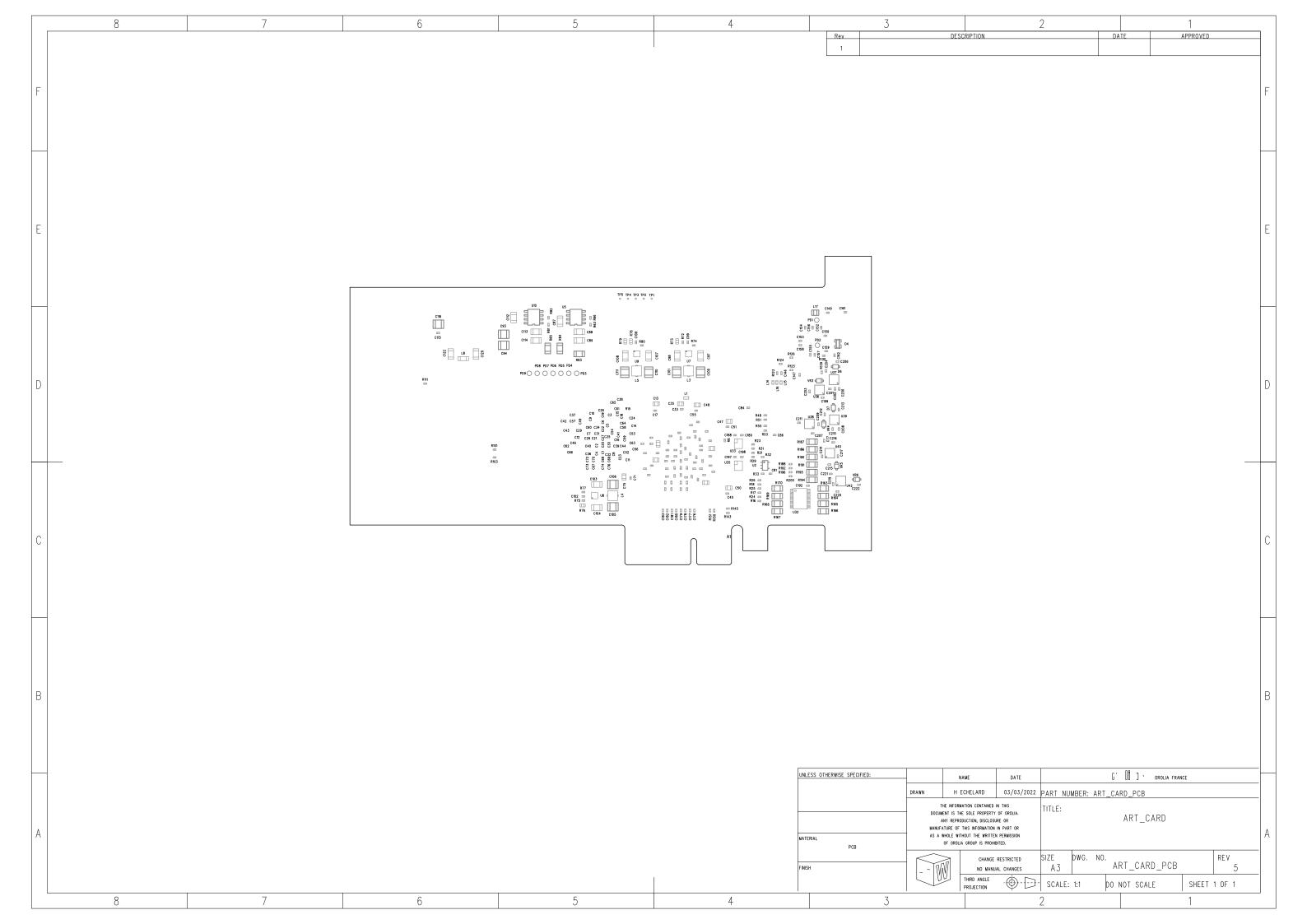


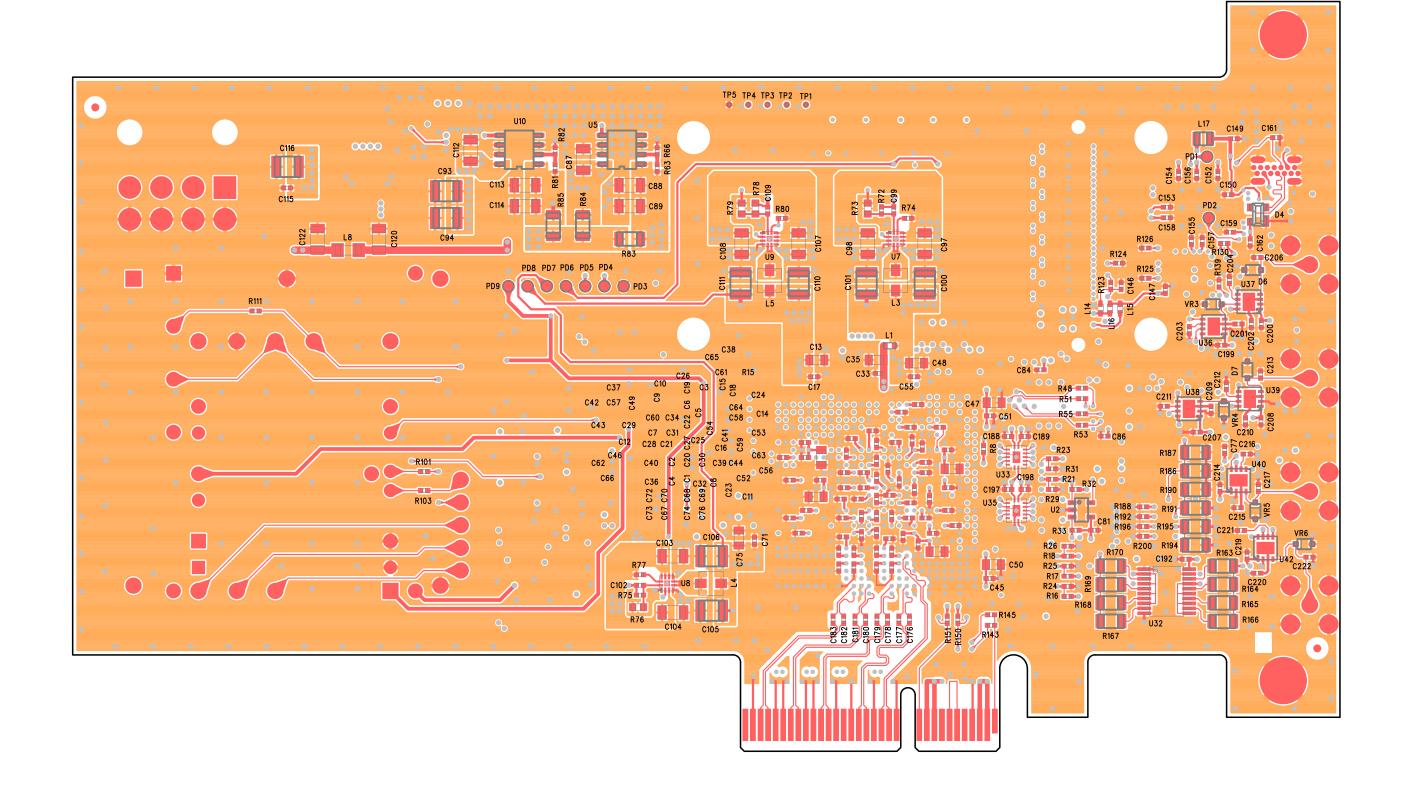




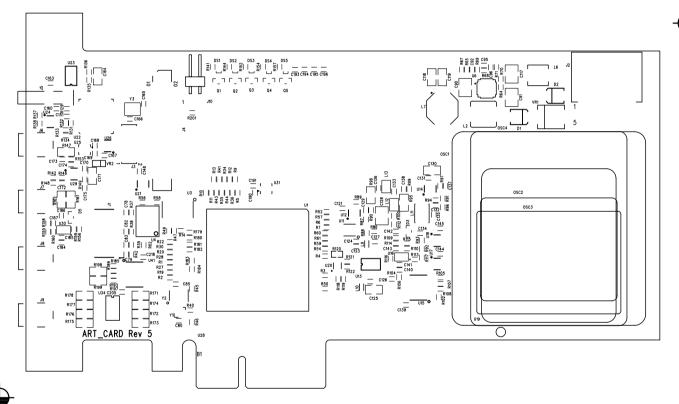


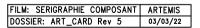




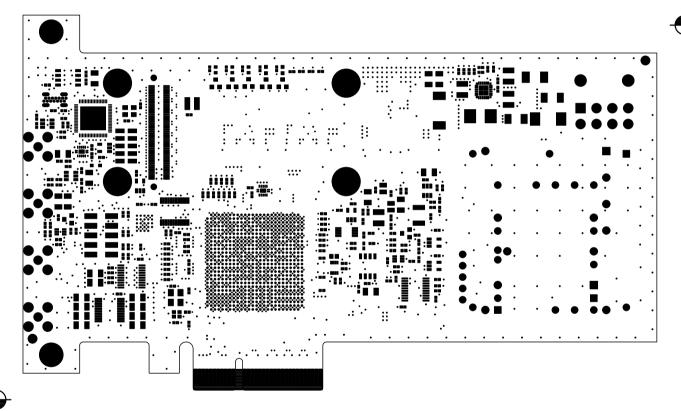


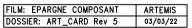




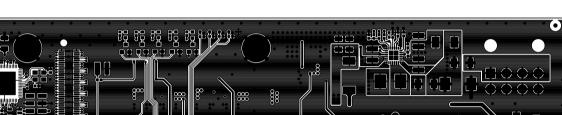


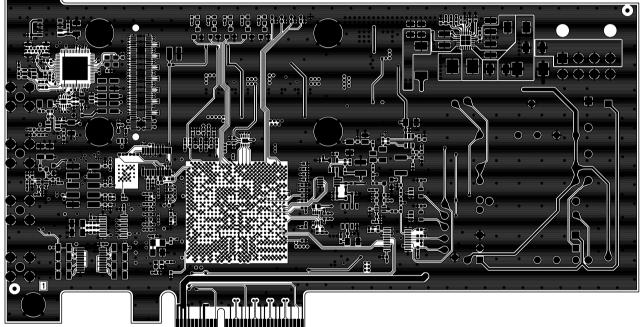










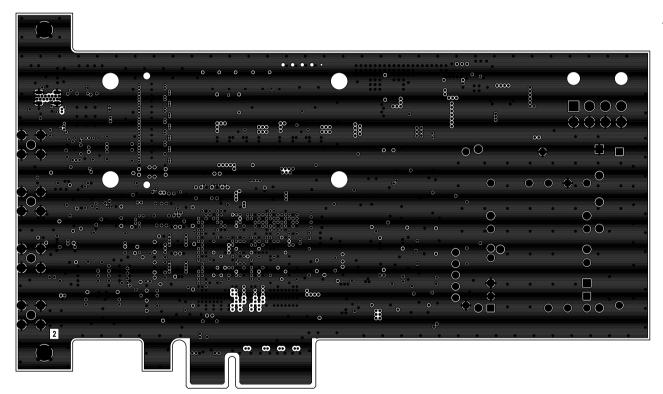




FILM: COMPOSANT	ARTEMIS
DOSSIER: ART_CARD Rev 5	03/03/22





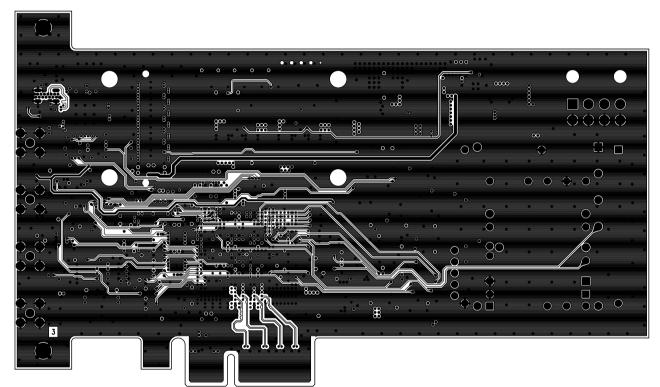




FILM: COUCHE INTERNE 1	ARTEMIS
DOSSIER: ART_CARD Rev 5	03/03/22





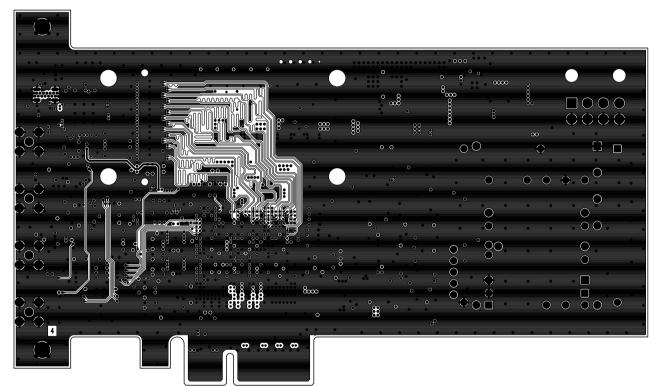




FILM: COUCHE	INTERNE 2	ARTEMIS
DOSSIER: ART	_CARD Rev 5	03/03/22





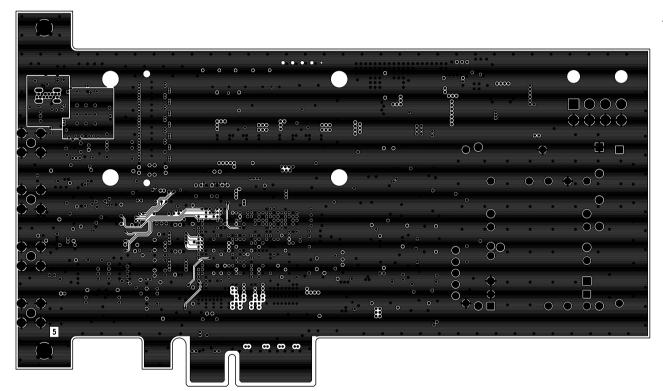




FILM: COUCHE	INTERNE 3	ARTEMIS
DOSSIER: ART	_CARD Rev 5	03/03/22





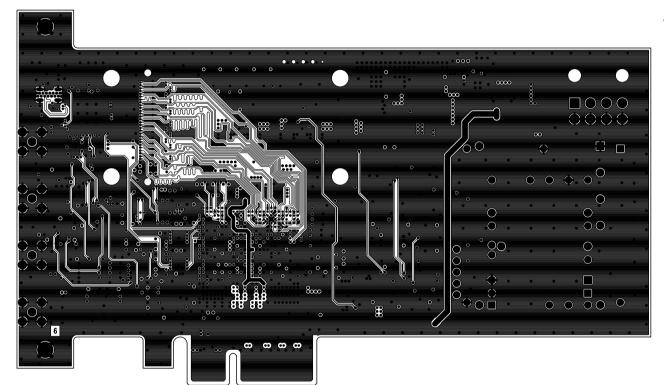




FILM: COUCHE	INTERNE 4	ARTEMIS
DOSSIER: ART	_CARD Rev 5	03/03/22





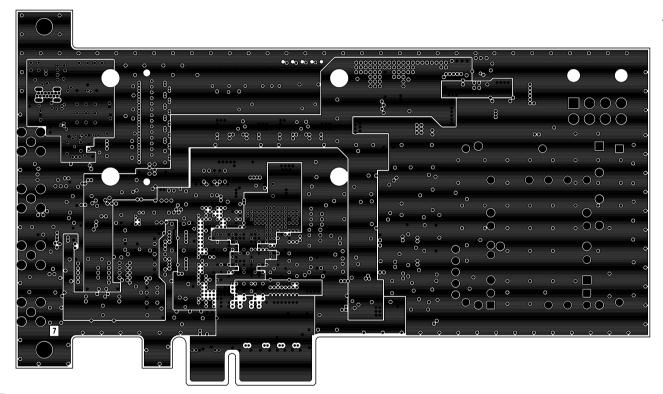




FILM: COUCHE	INTERNE 5	ARTEMIS
DOSSIER: ART	_CARD Rev 5	03/03/22





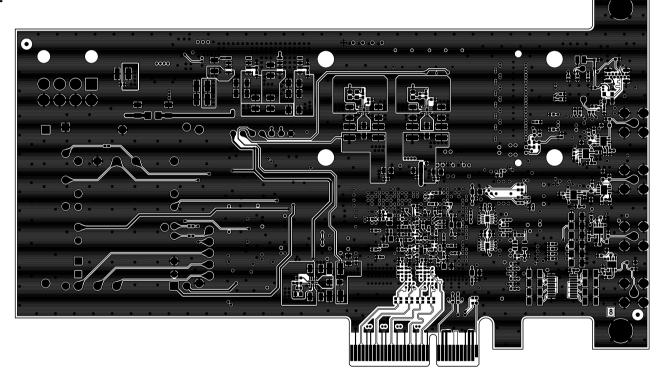




FILM: COUCHE INTERNE 6	ARTEMIS
DOSSIER: ART_CARD Rev 5	03/03/22

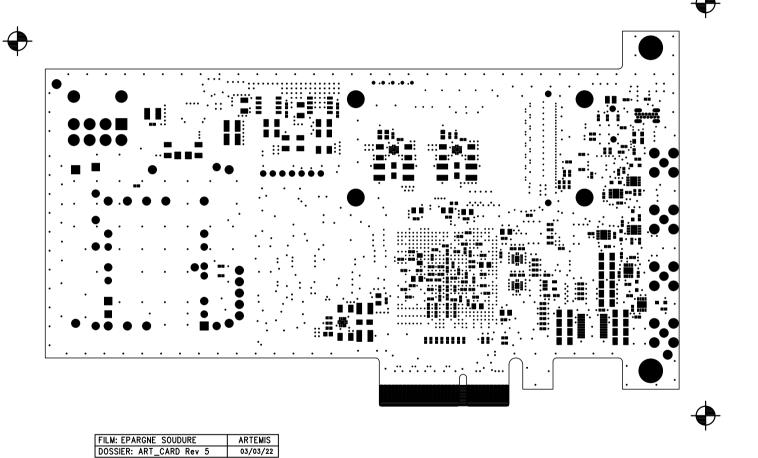






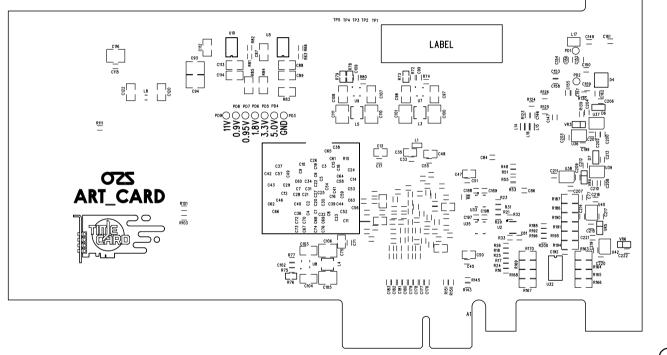
FILM: SOUDURE	ARTEMIS
DOSSIER: ART_CARD Rev 5	03/03/22





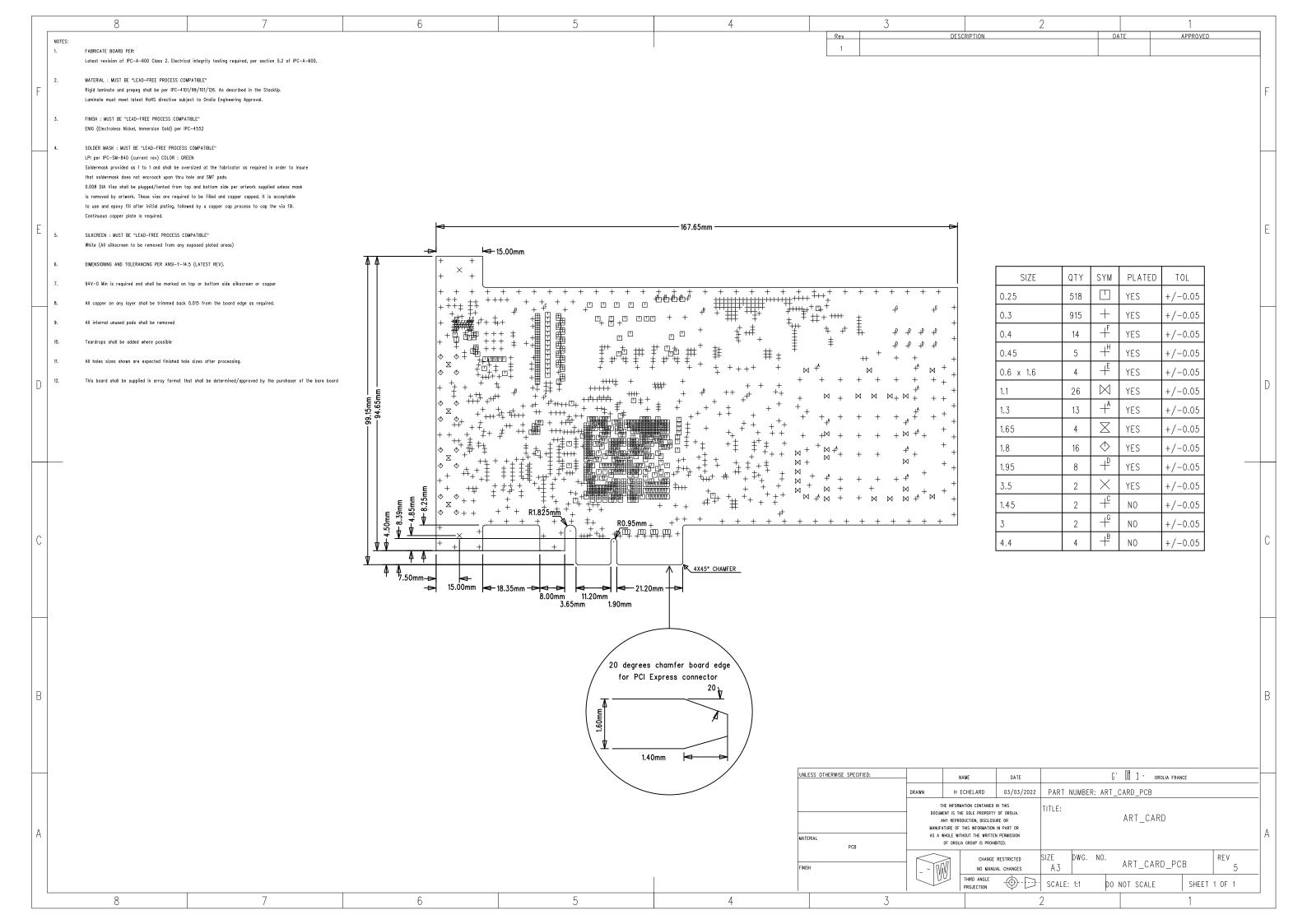






FILM: SERIGRAPHIE SOUDURE ARTEMIS
DOSSIER: ART_CARD Rev 5 03/03/22







Angers Technopole 1 bis Avenue du Bois l'Abbé 49070 BEAUCOUZÉ FRANCE

Phone: +33(0)2-41-48-98-68 p.benoit@artemis-cad.com

www.artemis-cad.com

TECHNICAL SPECIFICATION

IPC-A-600

CUSTUMER: OROLIA

MANUFACTURER:

PCB Reference :	ART_CARD	Index: Rev 5		
✓ PCB Unit	Unit PCB dimensions :	167.65 X 99.15 mm		
Panel PCB: 0	Panel dimensions :	0 X 0 mm		
Material: FR4	Surface :	1.66 dm ² Track / Gap: 0.15 / 0.15 mm		
PCB Type :	MC8 Finish	h Copper Thikness (µm) : 12µ 17,5µ 35µ 40µm		
PCB Thickness (mm):	16/10	External Layer :		
		Intern Layer : ✓		
Technology ✓	Plated Trough Hole	Via type: Hole / pads ratio: 0,25/0,55		
✓ Traditional	Press-fit Hole	✓ Traditional Via Via in pad		
✓ SMT	Autre	Laser Via Stacked Staggered		
Surface Treatement Finished		Blinded Via Couche départ et d'arrivée		
✓ Ni/Au Chemical	Sn/Pb surfondu	Buried Via Couche départ et d'arrivée		
Sn/Cu HAL	Autre	Filled Via Resin Copper		
Peelable Solder Mask	Standard	ТОР ВОТТОМ		
Solder Mask ✓	Photo-imageable	Green ✓ TOP ✓ BOTTOM		
Silkscreen ✓	Ink	White ✓ TOP ✓ BOTTOM		
Electrical Test		✓ Yes No		
✓ Impedance control :		✓ Produced Measured		
50 ohms		_ <u></u>		
✓ Differential Pairs :		✓ Produced Measured		
85 ohms on layer 1, 3 and 8 ; 9	0 ohms on layer 4, 5 and	8		
✓ Stack-up :	voir avec le fabricant P	CB et selon contraintes.		
Milling	Milling Diameter :	0 mm		
Comments :				
Construire un empilage pour avoir avoir des lignes 50 ohms en 150µm (classe de la carte)				
Pour les lignes 85 et 90 ohms, ajuster les largeurs si necessaire en gardant les isolations.				